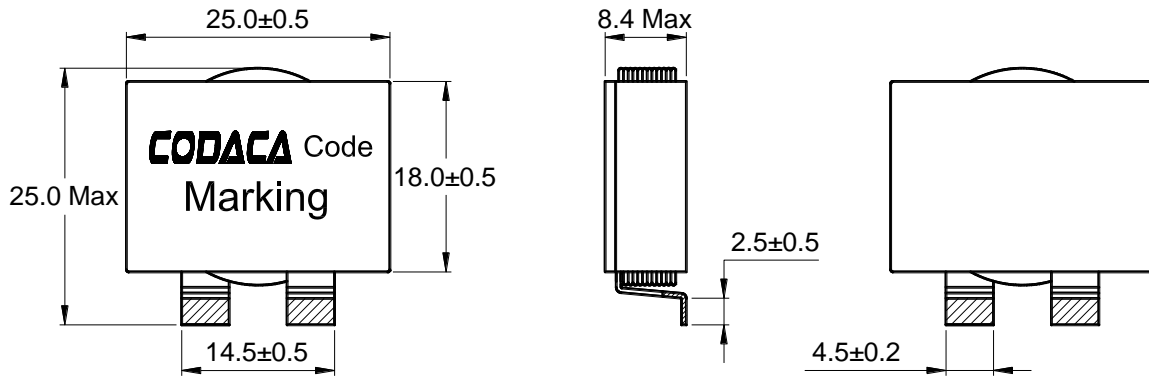




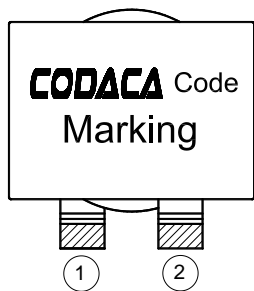
**Outline:
产品概要**

- Assemblage design, sturdy structure.
组立式设计，结构坚固。
- Small volume, high current, low magnetic loss, low ESR, small parasitic capacitance.
小体积，大电流，低磁损，低阻抗，寄生电容小。
- Closed magnetic circuit, ultra low buzz noise.
磁路闭合，超低蜂鸣噪音。
- Temperature rise current and saturation current is less influenced by environment.
温升电流及饱和电流受环境条件影响小。
- Operating temperature : -40°C ~ +125°C (Including coil's temperature rise)
工作温度：-40°C ~ +125°C (包含线圈发热)

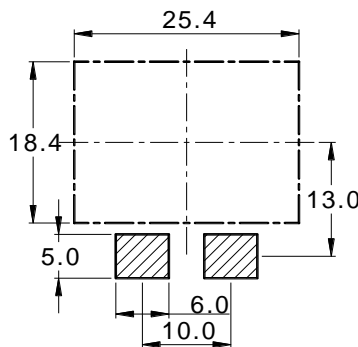
**1 Appearance and dimensions (mm)
外形尺寸**



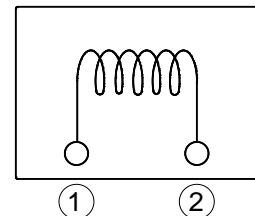
**2 Marking
印字标识**



**3 Reference land pattern (mm)
参考基板尺寸**



**4 Schematic
原理图**



5 Electrical characteristics

电气特性

Part No. 型号	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max		
CSCE2580-1R5M	1.50	1.60	1.80	60.0	28.0
CSCE2580-3R3M	3.30	2.60	3.00	38.0	26.0
CSCE2580-4R7M	4.70	2.60	3.00	30.0	26.0
CSCE2580-6R8M	6.80	3.10	3.50	23.0	23.0
CSCE2580-100M	10.0	4.96	6.00	20.0	20.0
CSCE2580-150M	15.0	4.96	6.00	11.0	20.0
CSCE2580-220M	22.0	4.96	6.00	8.00	20.0
CSCE2580-330M	33.0	4.96	6.00	6.00	20.0
CSCE2580-560M	56.0	4.96	6.00	3.00	20.0

■ All data is tested based on 25°C ambient temperature.

所有数据基于环境温度 25°C 条件下测试。

※1 Inductance measure condition at 100kHz, 0.1V.

电感测试条件为 100kHz, 0.1V。

※2 Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.

饱和电流: 电感值下降其初始值的 20% 时所加载的实际直流电流值。

※3 Temperature rise current: the actual value of DC current when the temperature rise is $\Delta T 40^{\circ}\text{C}$ ($T_a=25^{\circ}\text{C}$).

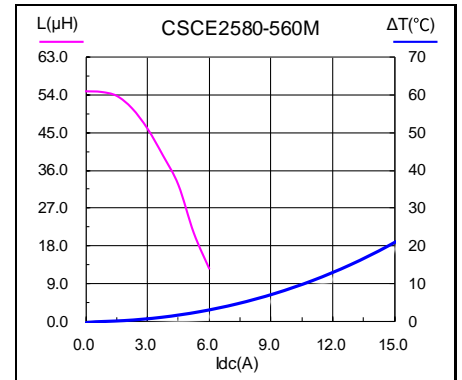
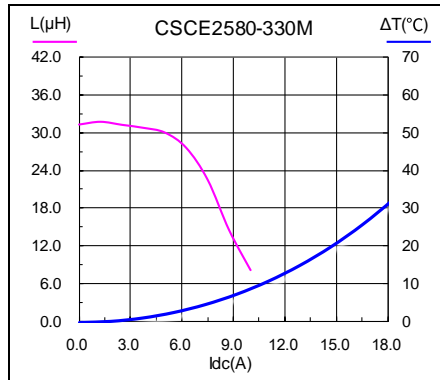
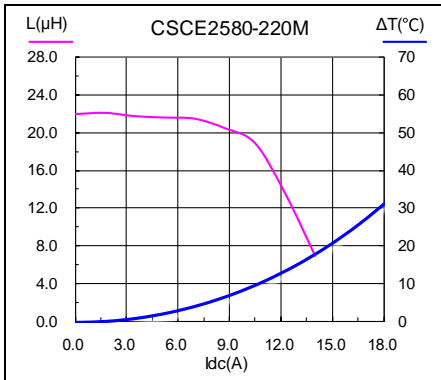
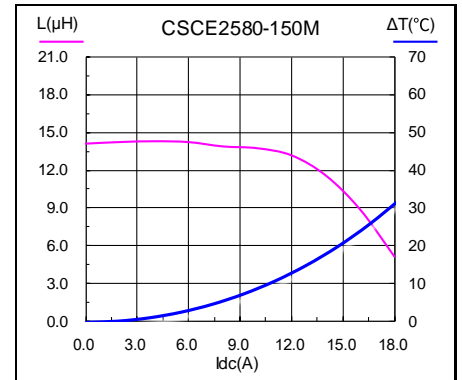
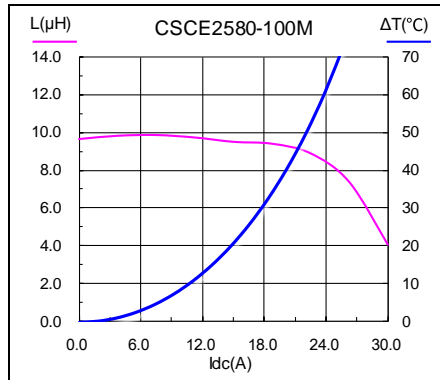
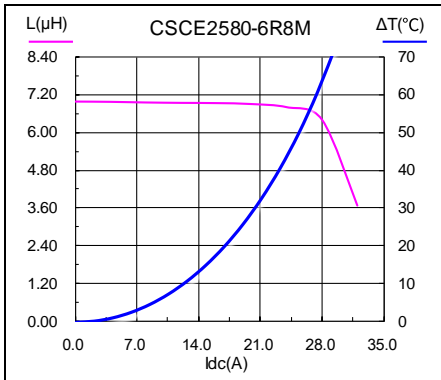
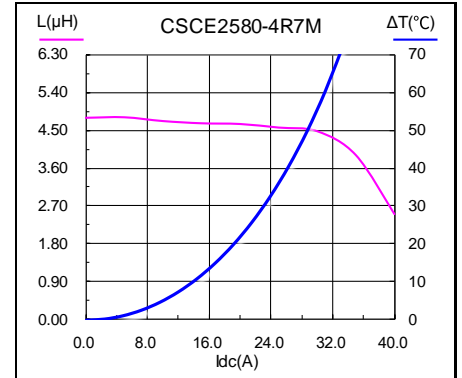
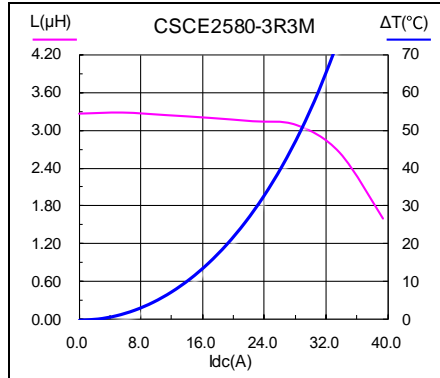
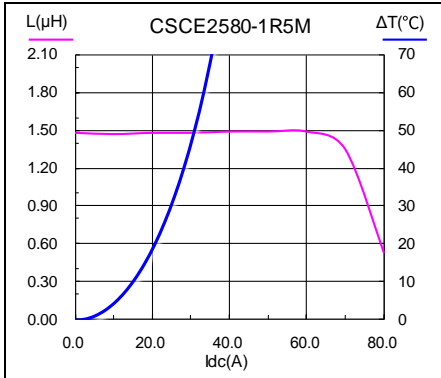
温升电流: 使产品温度上升到 $\Delta T 40^{\circ}\text{C}$ 时所加载的实际直流电流值 ($T_a=25^{\circ}\text{C}$)。

※ Special remind: Circuit design, component placement, PWB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒: 线路设计, 组件布局, 印刷电路板(PWB)尺寸及厚度, 散热系统等均会影响产品温度。

请务必在最终应用时, 验证产品发热状况。

6 Saturation current VS temperature rise current curve 饱和电流 VS 温升电流曲线

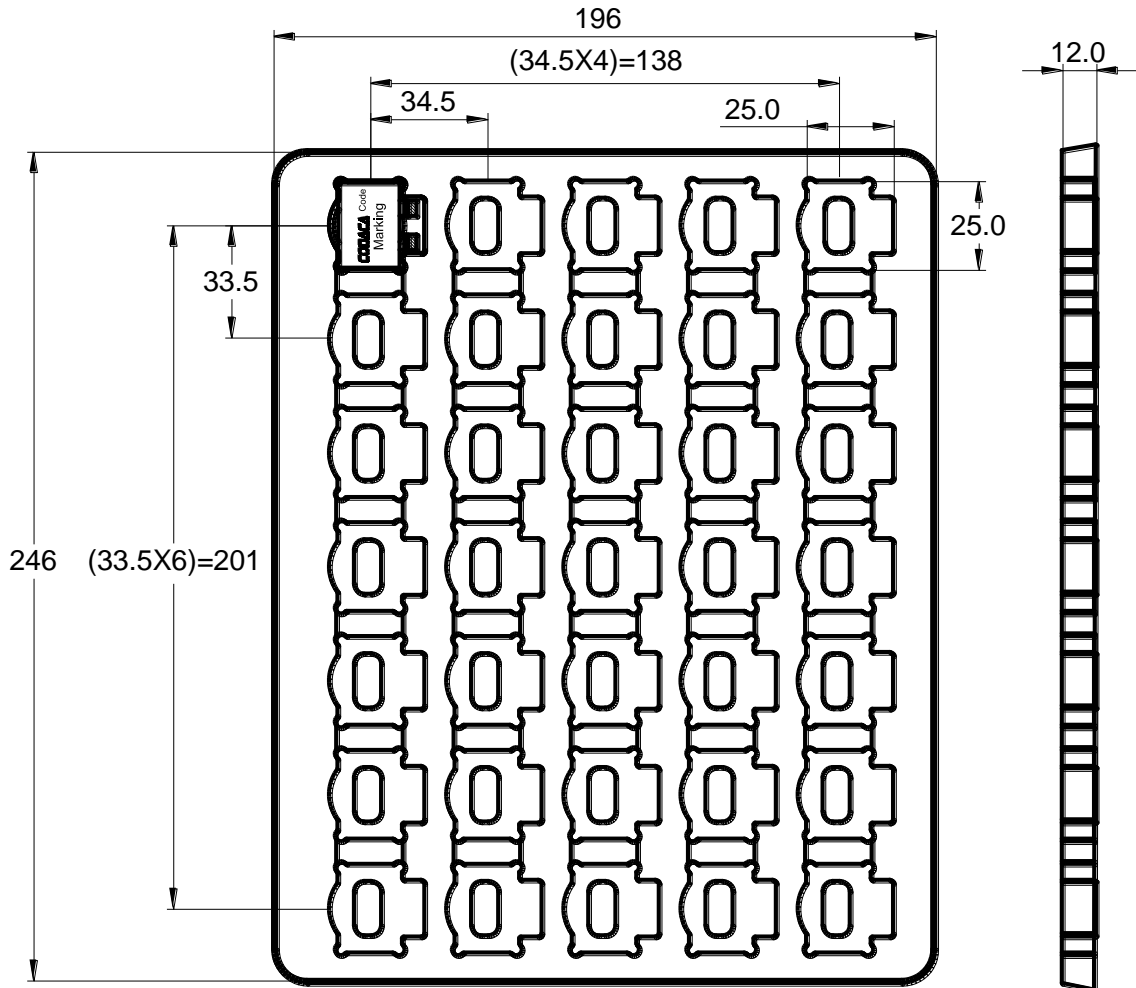


7 Packing specification

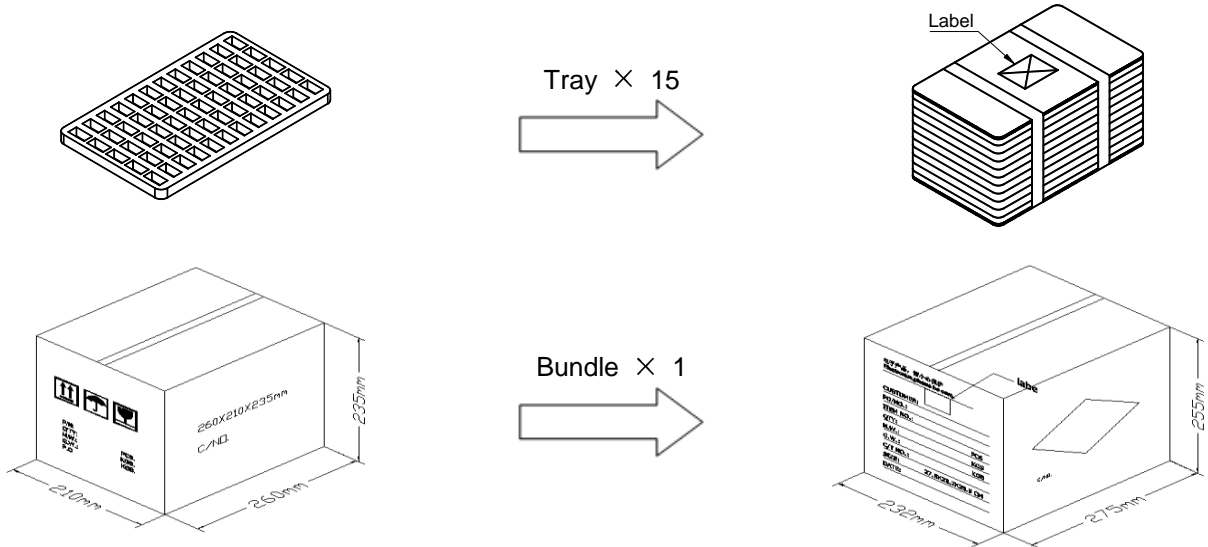
包装规格

7.1 Plastic tray dimensions (mm)

吸塑盘尺寸



7.2 Packing 包装



7.3 Carton dimensions and packing quantity 包装箱尺寸和包装数量

■ Inner Carton : 260×210×235mm
内包装箱

■ Out Carton : 275×232×255mm
外包装箱

Product Series 产品系列	Quantity / Tray 数量 / 盘	Quantity / Bundle 数量 / 捆	Out Carton Quantity 外箱 包装总数量
CSCE2580	35pcs	(35×15) = 525pcs	(525×1) = 525pcs

7.4 Label making 标签标识

The following items will be marked on the tray of product label and shipping label.
以下项目将明确标识于产品吸塑盘标签以及运输标签上。

Production Label 产品标签
■ Part No. 产品型号
■ Electrical Information 产品电性信息
■ Quantity 数量
■ Packing No. 包装流水号

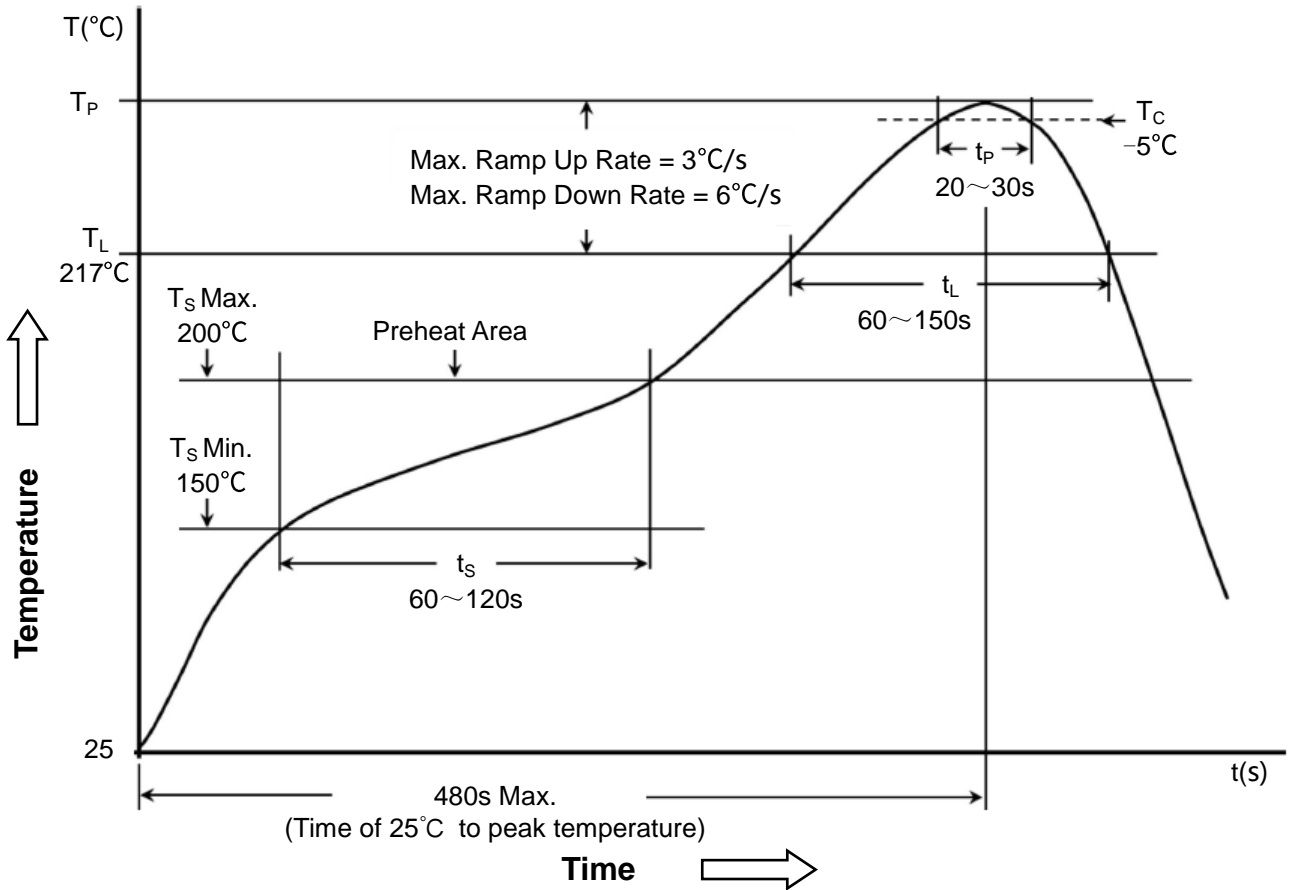
Shipping Label 运输标签
■ Customer Name 客户名称
■ Customer Part No. 客户型号
■ Supplier Part No. 供应商型号
■ Supplier Name 供应商名称
■ Country of origin 产品产地

8 Soldering specification

焊接规格

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (Tp)

封装体峰值温度(Tp)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。